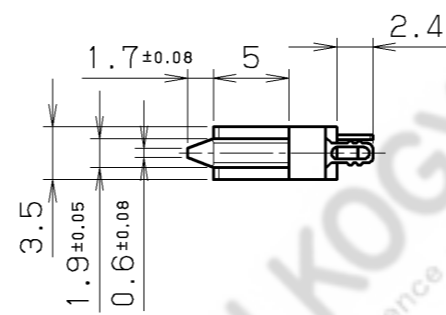
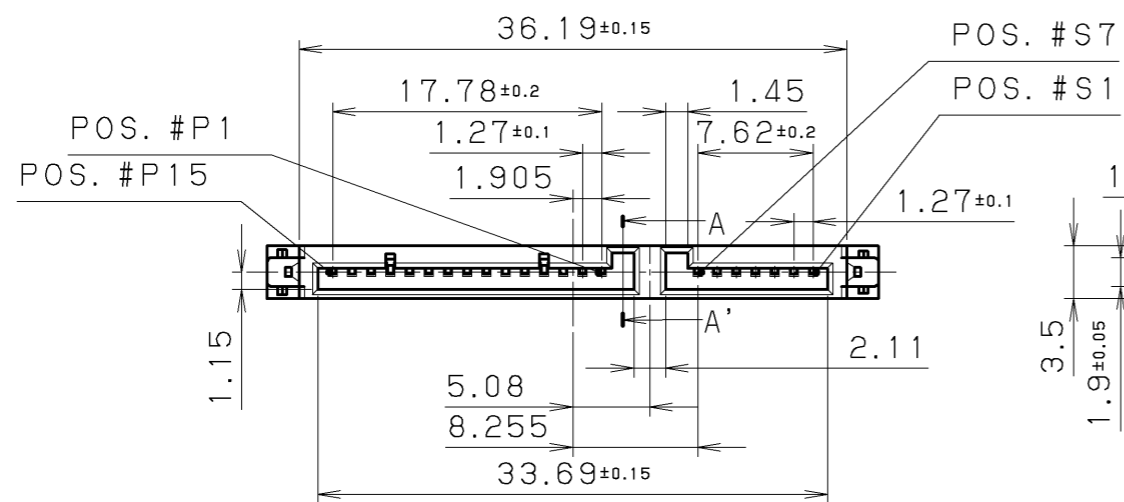


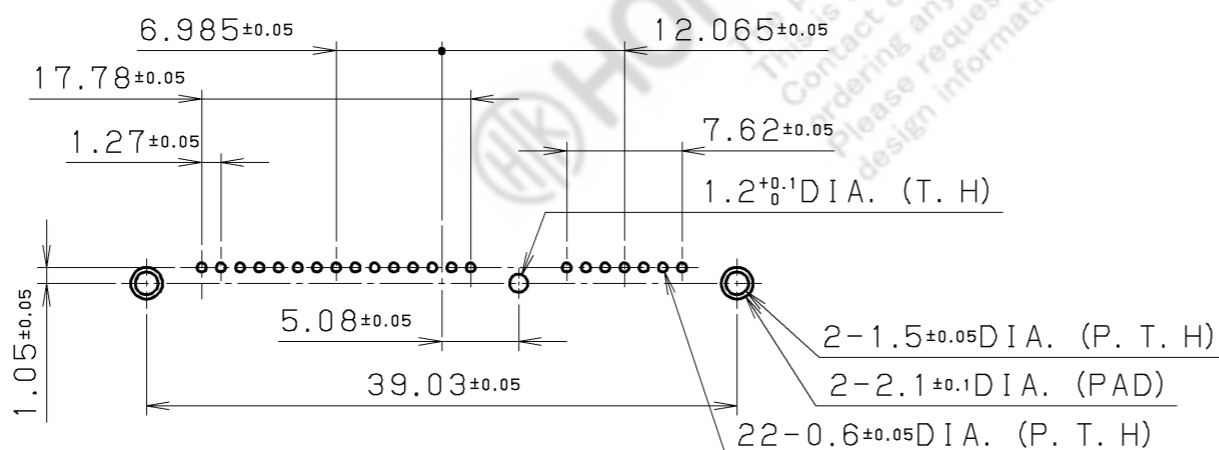
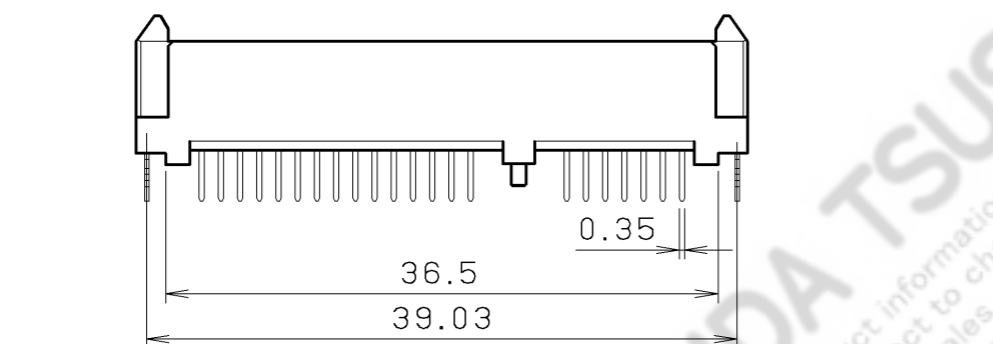
1.4±0.15 (POS. #P4&P12 ONLY)

SECTION A-A'
SCALE 5:1



NOTE 1. CONTACT PLATING:
CONTACT AREA: GOLD 0.2μm MIN.
TERMINATION AREA: TIN/COPPER 2μm MIN.
ALL OVER NICKEL UNDERPLATED.
2. CONNECTOR PIN ASSIGNMENTS

•S1 - GROUND	•P1 - 3.3V
•S2 - A+	•P2 - 3.3V
•S3 - A-	•P3 - 3.3V
•S4 - GROUND	•P4 - GROUND
•S5 - B-	•P5 - GROUND
•S6 - B+	•P6 - GROUND
•S7 - GROUND	•P7 - 5V
	•P8 - 5V
	•P9 - 5V
	•P10 - GROUND
	•P11 - GROUND
	•P12 - GROUND
	•P13 - 12V
	•P14 - 12V
	•P15 - 12V



RECOMMENDED P. C. B. LAYOUT
PCB THICKNESS: 1.6±0.15mm
(Connector side)

△				3	BOARD LOCK	COPPER ALLOY	2	TIN/COPPER	
△				2	CONTACT	COPPER ALLOY	22	SEE NOTE#1	
△				1	INSULATOR	LCP	1		UL94V-0 BLACK

LTR.	DATE	BY	REV.	DESCRPT	No.	PART NAME	MATERIAL	QTY	FINISH	NOTE
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DATE	SCALE	UNIT	3RD. A. P	HONDA TSUSHIN KOGYO CO., LTD.						
Dec.12.2005	2 / 1	mm (INCH)								
APP. DATE&REV.										

DR.	DE.	CHK.	CHK.	APP.	NAME	SERIAL ATA VERTICAL HOST RECEPTACLE CONNECTOR	REV.
M. KASHIHARA	M. KASHIHARA	K. KASAI	—	K. OHNISHI	PART NO.	HSA-SP22SFDG	